Panasonic CONNECT

2026

Device-related systems

Plasma cleaner

Catalogue

Model ID

PSX307

Model No.

NM-EFP1A

- **Chamber configuration that achieves both in-plane uniformity and etching rate.**
- **Our original lifting unit can handle PCBs that are thin and warped and PCBs with components on the backside.**
- **Our original plasma monitor function avoids abnormal discharge and enables damage-free processing.**
- **Traceability is ensured due to online operation.**

CE

*It may not conform to Machinery Directive and EMC Directive in case of optional configuration and custom-made specification.

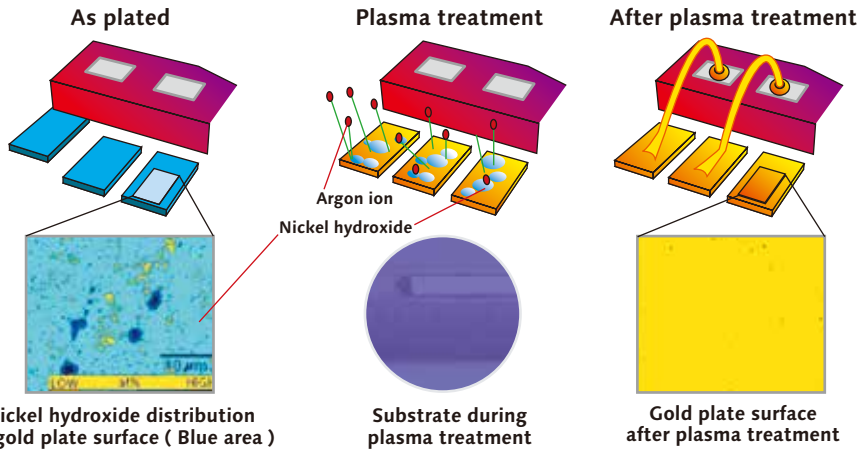
Model ID	PSX307
Model No.	NM-EFP1A
Cleaning Method Dimension	Parallel plate RF back-sputtering method
Gas for Electrical DischargeDimension *1	Ar (option : O_2)
Substrate Dimension	L 50 mm × W 20 mm to L 250 mm × W 75 *2 mm (S type) L 50 mm × W 20 mm to L 330 mm × W 120 mm (M type)
Substrate Thickness	0.5 mm to 2.0 mm
Dimension / Mass *3	W 930 mm × D 1 100 mm × H 1 450 mm / 555 kg W 2 113 mm × D 1 100 mm × H 1 450 mm / 850 kg (S type transfer system, including loader and unloader options.) W 2 266 mm × D 1 100 mm × H 1 450 mm / 725 kg (M type transfer system, including loader and unloader options.)
Power Souce *4	1-phase AC 200 V , 2.00 kVA (Full Load 5.00 kVA)
Pneumatic source	0.49 MPa or more , 6.5 L / min (A.N.R.)

Please refer to the specifications on details.

*1 : If the optional oxygen gas is selected as discharge gas , nitrogen gas is also required to dilute exhaust.
*2 : For W 70.1 mm to W 75 mm , the electrode in the chamber is required separately.
*3 : Tolerance of equipment dimensions is ± 5 mm , Touch panel and condition lamp is not included. Mass varies depending on configuration.
*4 : Compatible with 1-phase 208 / 220 / 230 / 240 V.

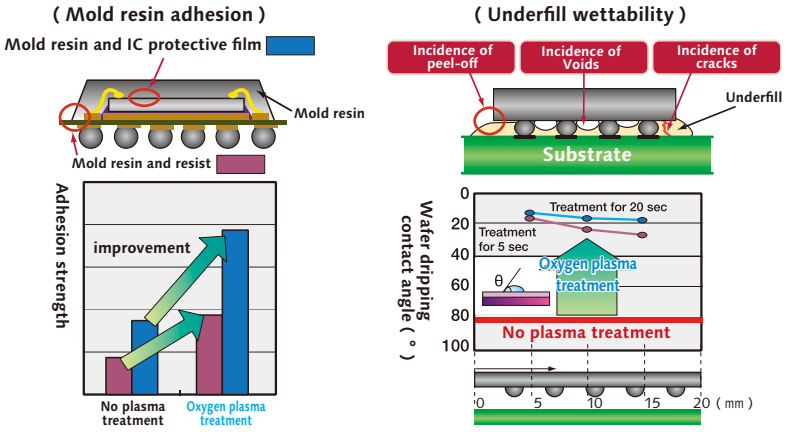
The reason why an extra-thin gold plated electrode can be used

When a extra-thin gold plated electrode is used , nickel compounds are formed on a surface after the heat treatment by the die-bonding cure.
These nickel compounds impair the wire bonding performance , thus it is said that a thin gold plated electrode is unsuitable for wire bonding.
However , the argob plasma treatment eliminates the nickel compounds , therefore stable wire bonding can be performed on an extra-thin and extra-cheap gold plated electrode.



Surface reforming by oxygen plasma

Surface reforming by oxygen radical improves mold resin adhesion and under-fill wettability. (option)



Transfer system options

M type
Transfer system ,
loader , and unloader.

S type
Transfer system ,
loader , and unloader.

⚠ Safety Cautions

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

Panasonic Group products are built with the environment in mind. For details here Panasonic GREEN IMPACT

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